

Amendment to the Claims

1. (Currently Amended) A manufacturing method for electronic component-mounted components, which comprises:

embedding an electronic component into a base made of a resin sheet;

removing at least a portion of the base by carrying out at least one treatment of electrical discharge machining, laser beam machining, ion beam machining and electron beam machining to a machining face of the base, and thereby exposing electrodes of the embedded electronic component; and

forming a circuit pattern in contact with the exposed electrodes.

2. (Currently Amended) A manufacturing method for electronic component-mounted components, which comprises:

embedding an electronic component into a base;

removing at least a portion of the base by carrying out at least one treatment of electrical discharge machining, laser beam machining, ion beam machining and electron beam machining to a machining face of the base, and thereby exposing electrodes of the embedded electronic component;

forming a circuit pattern in contact with the exposed electrodes;
and

~~The manufacturing method for the electronic component-mounted components according to claim 1, which further comprises:~~

forming a through hole to penetrate the machining face and a rear face opposite to the machining face while carrying out the treatment to the base, and

while forming the circuit pattern, forming an electric connection between the machining face and the rear face via the through hole by at least one of conductive sputtering, vapor deposition and filling a conductive material.

3. (Original) The manufacturing method for the electronic component-mounted components according to claim 1, wherein the electrodes of the electronic component have projecting electrodes, and the exposing operation after the embedding into the base is to expose the projecting electrodes.

4. (Original) The manufacturing method for the electronic component-mounted components according to claim 1, wherein the circuit pattern forming operation forms at least one of a conductor routing, a metal thin film capacitor, a coil and a resistance in contact with the exposed electrodes by any one of plating, ion plating, sputtering and vapor deposition.

5. (Original) The manufacturing method for the electronic components-mounted components according to claim 1, wherein the circuit pattern forming operation forms the circuit pattern by printing a solder paste or conductive adhesive on the exposed electrodes, then heating and hardening the solder paste or conductive adhesive.

6. (Original) The manufacturing method for the electronic component-mounted components according to claim 1, wherein embedding the electronic component into the base is carried out to a plurality of electronic components in the same process, and after the circuit pattern is formed, the base is cut so as to correspond to respective electronic component-mounted components.

7. (Currently Amended) The manufacturing method for the electronic component-mounted components according to claim 1, wherein embedding the electronic components into the base is carried out by heat press, the base is a ~~thermoplastic sheet~~ formed of any one of polyvinyl chloride, polycarbonate, acrylonitrile butadiene styrene, thermoplastic polyimide and polyethylene terephthalate and has a thickness of 0.010-2.000mm, a glass transition point of the base is not lower than 333K and not higher than 423K, the electronic component has a thickness smaller than that of the base, electrodes of the electronic component have a height of 0.0005-0.1mm, and the base at the heat

press time is set to be a temperature higher by 50K or more than the glass transition point and not higher than 473K.

8. (Currently Amended) A manufacturing method for electronic component-mounted completed products, which comprises:

manufacturing electronic component-mounted components by a manufacturing method for electronic component-mounted components;

stacking the electronic component-mounted components or a base of the electronic component-mounted components in a thickness direction of the base after the manufacturing operation; and

executing a laminating process after the stacking operation,

the manufacturing method for electronic component-mounted components including:

embedding an electronic component into the base, which is formed of a resin sheet,

removing at least a portion of the base by carrying out at least one treatment of electrical discharge machining, laser beam machining, ion beam machining and electron beam machining to a machining face of the base, and thereby exposing electrodes of the embedded electronic component, and

forming a circuit pattern in contact with the exposed electrodes.

9. (Currently Amended) An electronic component-mounted completed product manufactured by a manufacturing method for electronic component-mounted completed products, the manufacturing method comprising:

manufacturing electronic component-mounted components by a manufacturing method for electronic component-mounted components;

stacking the electronic component-mounted components or a base of the electronic component-mounted components in a thickness direction of the base after the manufacturing operation; and

executing a laminating process after the stacking operation,

the manufacturing method for electronic component-mounted components including:

embedding an electronic component into the base, which is formed of a resin sheet,

removing at least a portion of the base by carrying out at least one treatment of electrical discharge machining, laser beam machining, ion beam machining and electron beam machining to a machining face of the base, and thereby exposing electrodes of the embedded electronic component, and

forming a circuit pattern in contact with the exposed electrodes.

10. (New) The manufacturing method for electronic component-mounted components according to claim 1, wherein the embedding operation comprises

pressing the electronic component into the resin sheet with a pressing tool while the resin sheet is supported on a heating stage.

11. (New) A manufacturing method for electronic component-mounted completed products according to claim 8, wherein the embedding operation comprises pressing the electronic component into the resin sheet with a pressing tool while the resin sheet is supported on a heating stage.

12. (New) The electronic component-mounted completed product manufactured by a manufacturing method for electronic component-mounted completed products according to claim 9, wherein the embedding operation comprises pressing the electronic component into the resin sheet with a pressing tool while the resin sheet is supported on a heating stage.